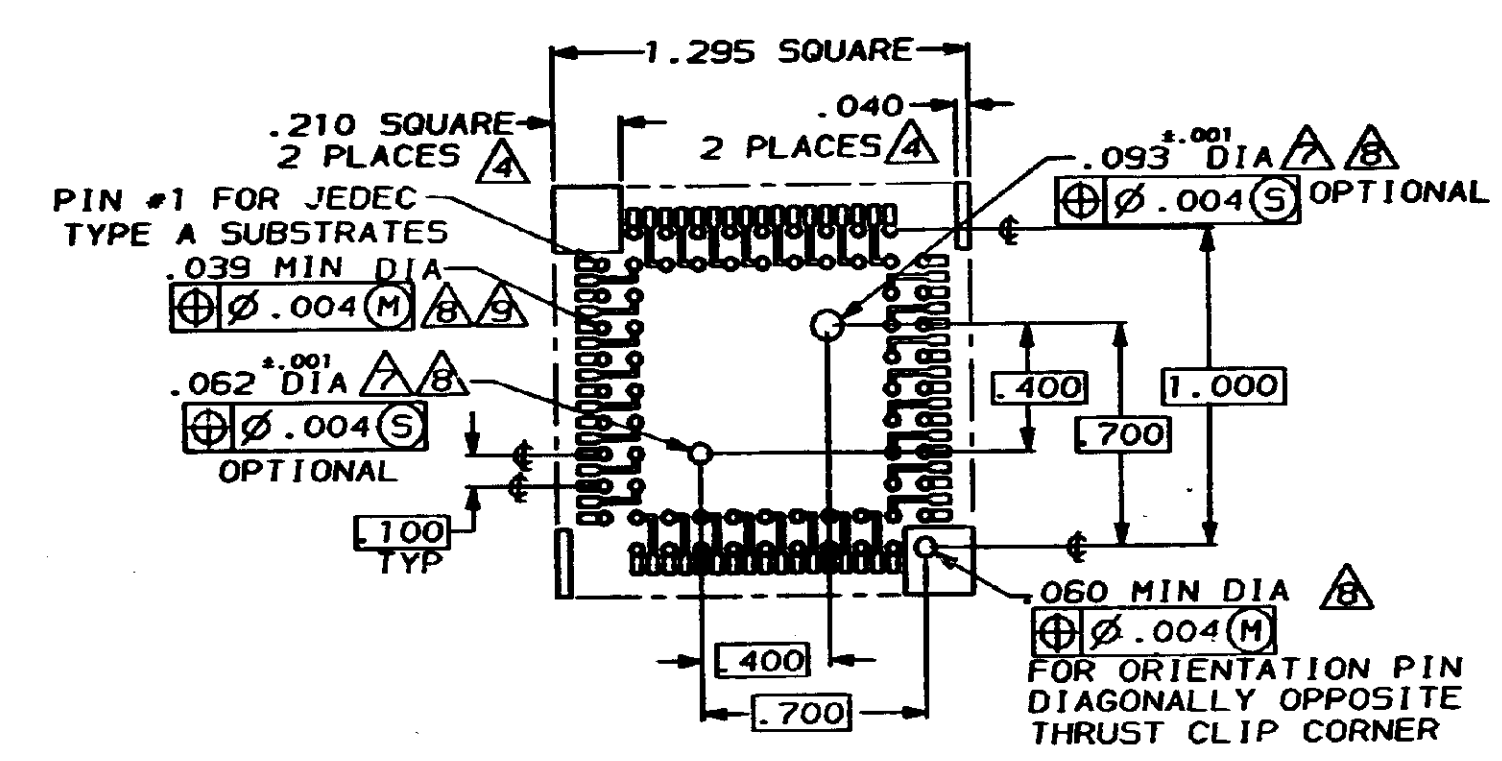
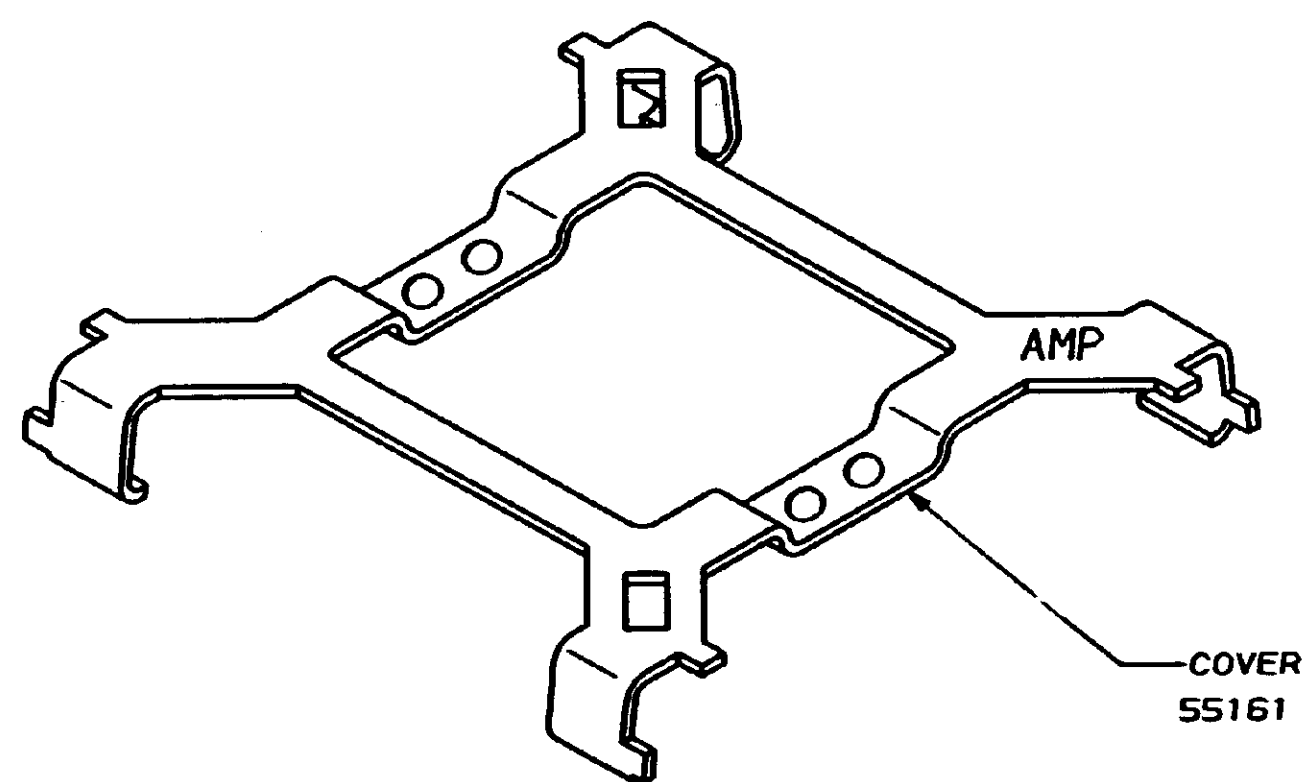
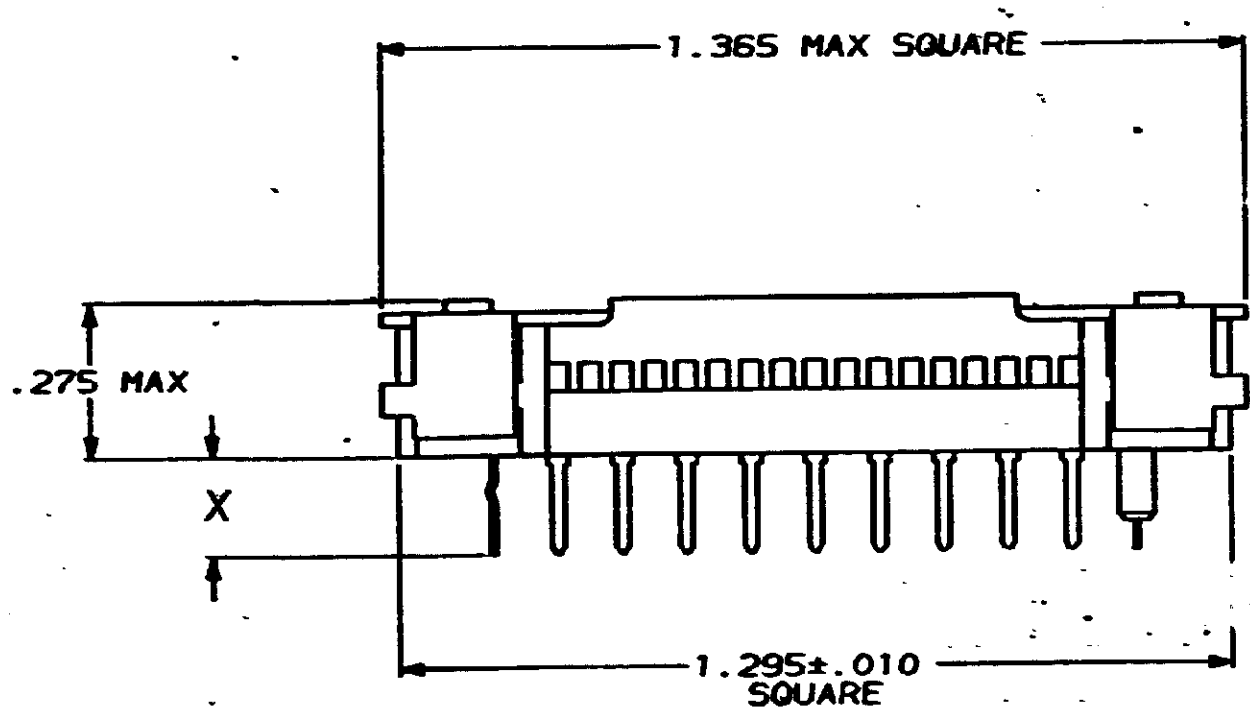
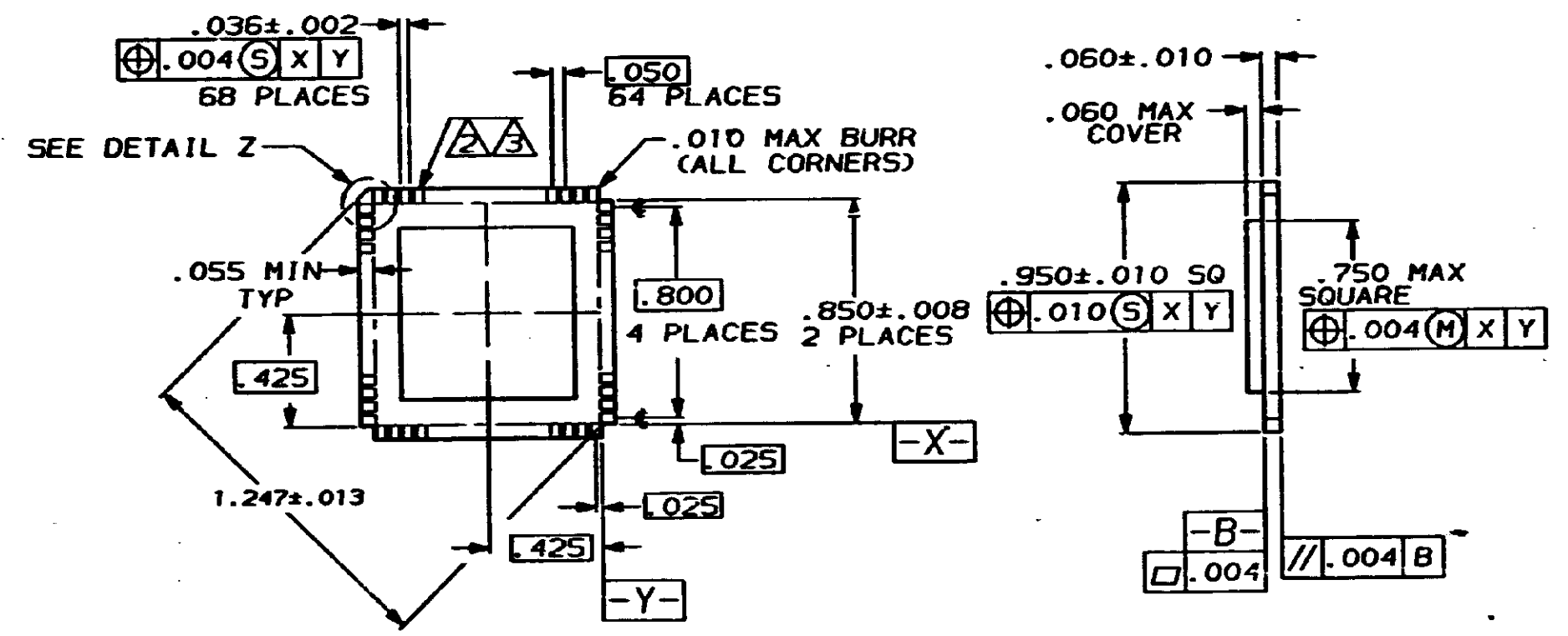
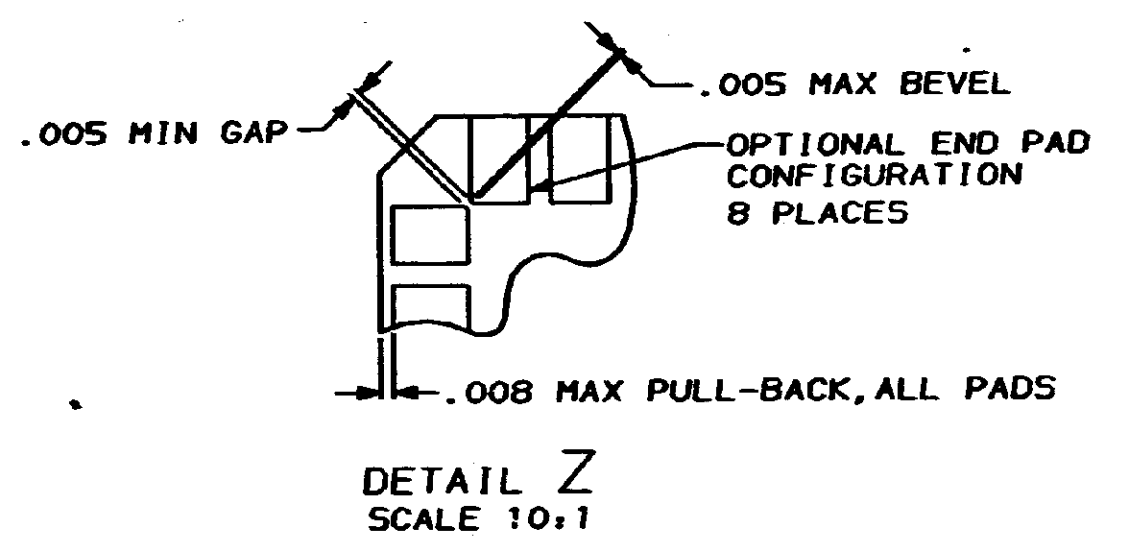
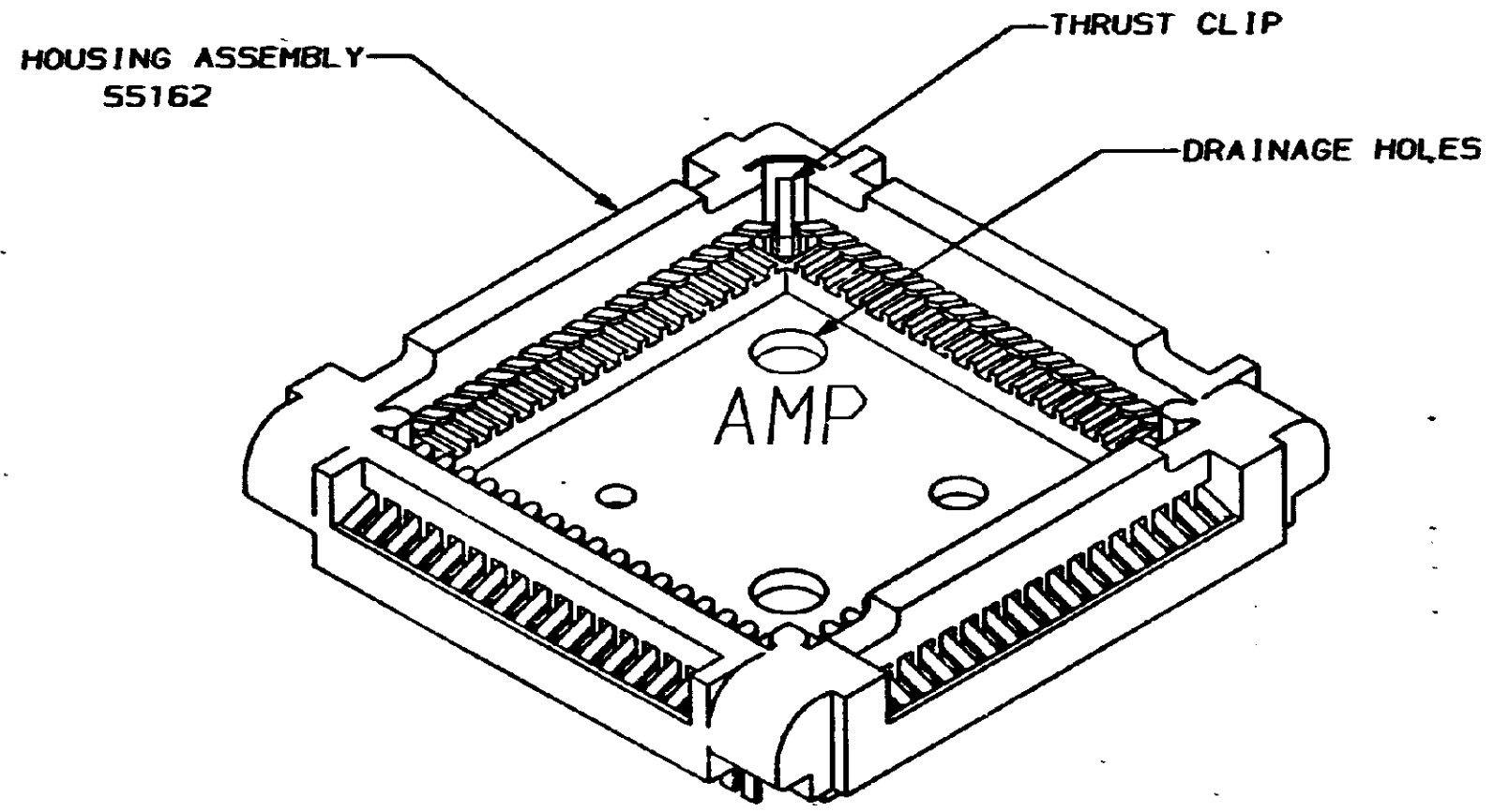


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REVOLUTIONS		DATE	APPROVED
P	F		
U		10-8-81	PC



- △ POST PLATED GOLD (MIL-G-45204) .000050 MIN THK OVER NICKEL (QQ-N-290) .000075 MIN THK ON SPRING CONTACT DIMPLES. MATTE TIN/LEAD (60-40%) .000150 MIN THK OVER NICKEL PL ON CONTACT SOLDER TAILS.
- △ SUBSTRATE PAD THICKNESS = .0003 MIN - .002 MAX.
- △ PAD PLATING: GOLD PL .00008 MIN OVER NICKEL PL .00010 MIN.
- △ CONNECTOR MAKES CONTACT WITH PCB SURFACE IN THESE LOCATIONS.
- 5 SUBSTRATE MUST HAVE METALLIZED PADS ON ONE SIDE ONLY DUE TO POSSIBLE SHORTING OF PADS BY COVER.
- 6 SHIPPED WITHOUT COVER INSTALLED.
- △ HOLES FOR USE WITH OPTIONAL SOCKET INSERTION TOOL, PART NO. 68381-1.
- △ WHEN OPTIONAL HOLES ARE USED, ALL HOLES MUST MEET SPECIFIED TOLERANCES SIMULTANEOUSLY.
- △ FOR ROBOTIC ASSEMBLY, THE MINIMUM PCB HOLE SIZE MUST BE INCREASED. CONSULT AMP ENGINEERING.



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES.		CONTRACT NO.		.110 ± .010 55159-2	
TOLERANCES ON:		DR LIVING		.140 ± .002 55159-1	
DECIMALS ± .005		D. HOLLINGSWORTH		X PART NO	
ANGLES ± 2°		CHK			
MATERIAL: THERMOPLASTIC CONTACTS, Be, Cu (90-C-533)		APPD		AMP INCORPORATED Harrisburg, Pa.	
COVER: STAINLESS STEEL		APPD		NAME	
FINISH: CONTACT PLATING: SEE NOTE		DSGN APPD 10/3/86		SOCKET, LHCC	
		RON SMITH		68 POSITION	
		OTHER APPD		SIZE	
				D 00779	
				DRAWING NO	
				55159	
				SCALE 4:1	
				REV T SHEET	

CUSTOMER DRAWING